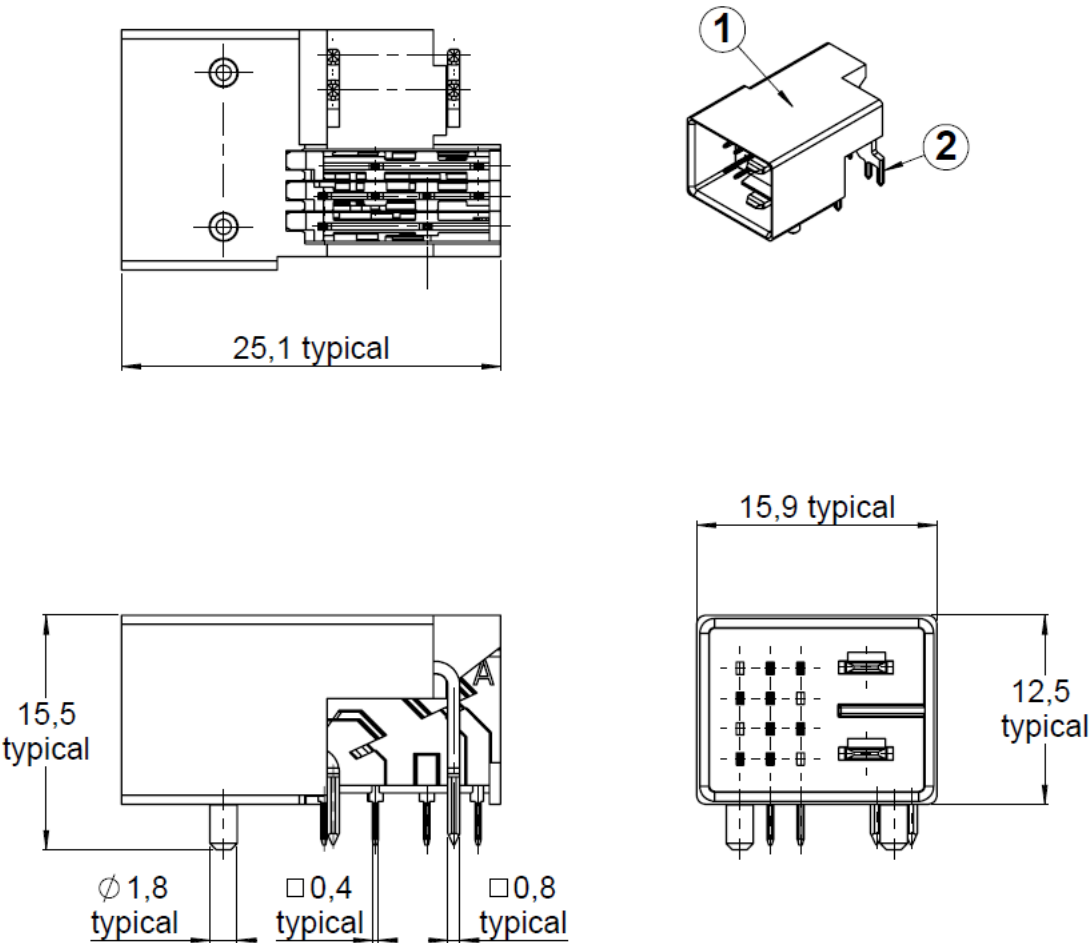


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All dimensions are in mm. Tolerances according ISO 2768 m-H

DESCRIPTION

REP	COMPONENT	MATERIALS	PLATING
1	Housing	PLASTIC	-
2	Contact	COPPER ALLOY	SN

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### GENERAL CHARACTERISTICS

<b>Mechanical</b> Mating endurance (cycles) Vibration Weight (g)	IEC 61300-2-2 EIA 364-28 -	100 - 2.0900
<b>Environmental</b> Operating temperature (°C) Storage temperature (°C) RoHS Flammability	IEC 61300-2-22 IEC 61300-2-22 - UL 94	-40 / +85 -65 / +85 Compliant V0
<b>Electrical</b>  <b>Signal pins</b> Working voltage (V AC Max) Contact resistance (mΩ max) Current rating (A) Insulation resistance (MΩ min)  <b>Signal Integrity performance</b> Cross talk  Impedance of pairs <b>IL</b> <b>RL</b>  <b>Power pins</b> Working voltage Current rating  Dielectric withstand voltage Insulation Resistance	- EIA 364-23B EIA 364-70A EIA 364-21C  - -  EIA 364-20 EIA 364-21  - - - EIA 364-20 EIA 364-21	300 55 1 A per contact (all contacts powered) 5000 (after environmental exposure)  Max. 300V AC (r.m.s.) 16A in combination with 1.5mm <sup>2</sup> conductors (16AWG) 20A in combination with 2.5mm <sup>2</sup> (14AWG) & 3.3mm <sup>2</sup> conductors (12AWG) 500V AC 5000MΩ minimum initial 1000MΩ minimum after environmental aging  Max. 300 AC or DC 16A with AWG16 wire (7xAWG24) 20A with AWG14 wire (7xAWG22) 5000MΩ minimum initial 1000MΩ minimum after environmental aging
<b>Others</b> Packaging	-	Packaging in Tape&Reel (Quantity per reel to be defined)

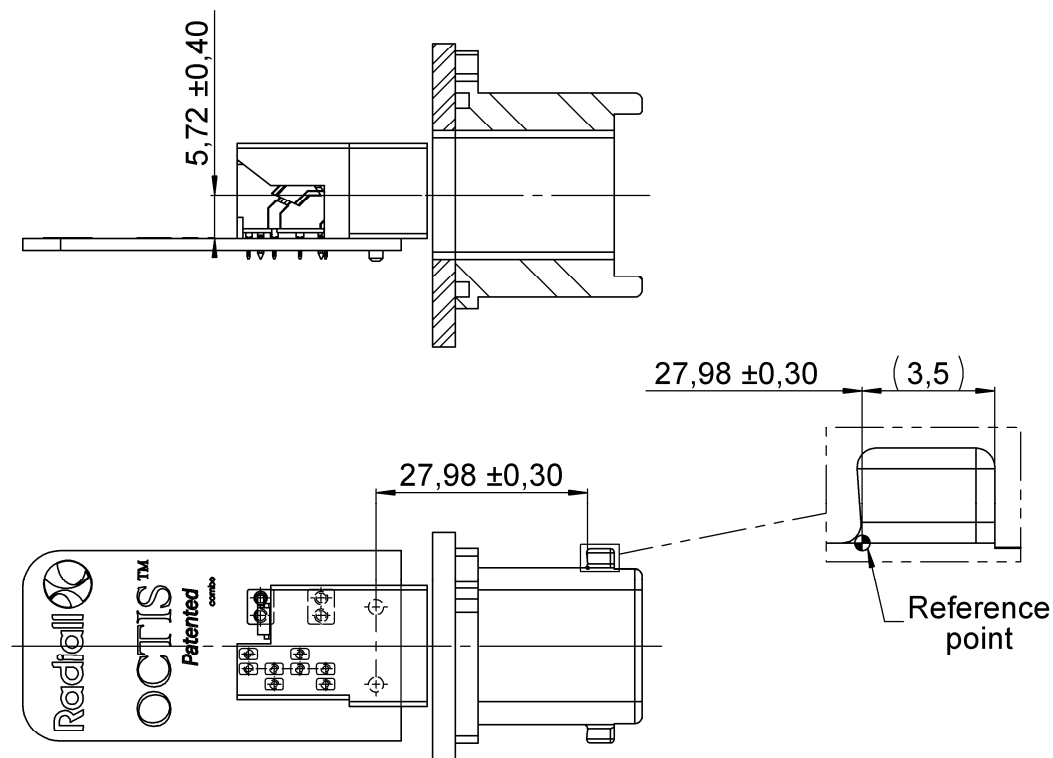
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**POSITIONING AND PATTERN DEFINITION**



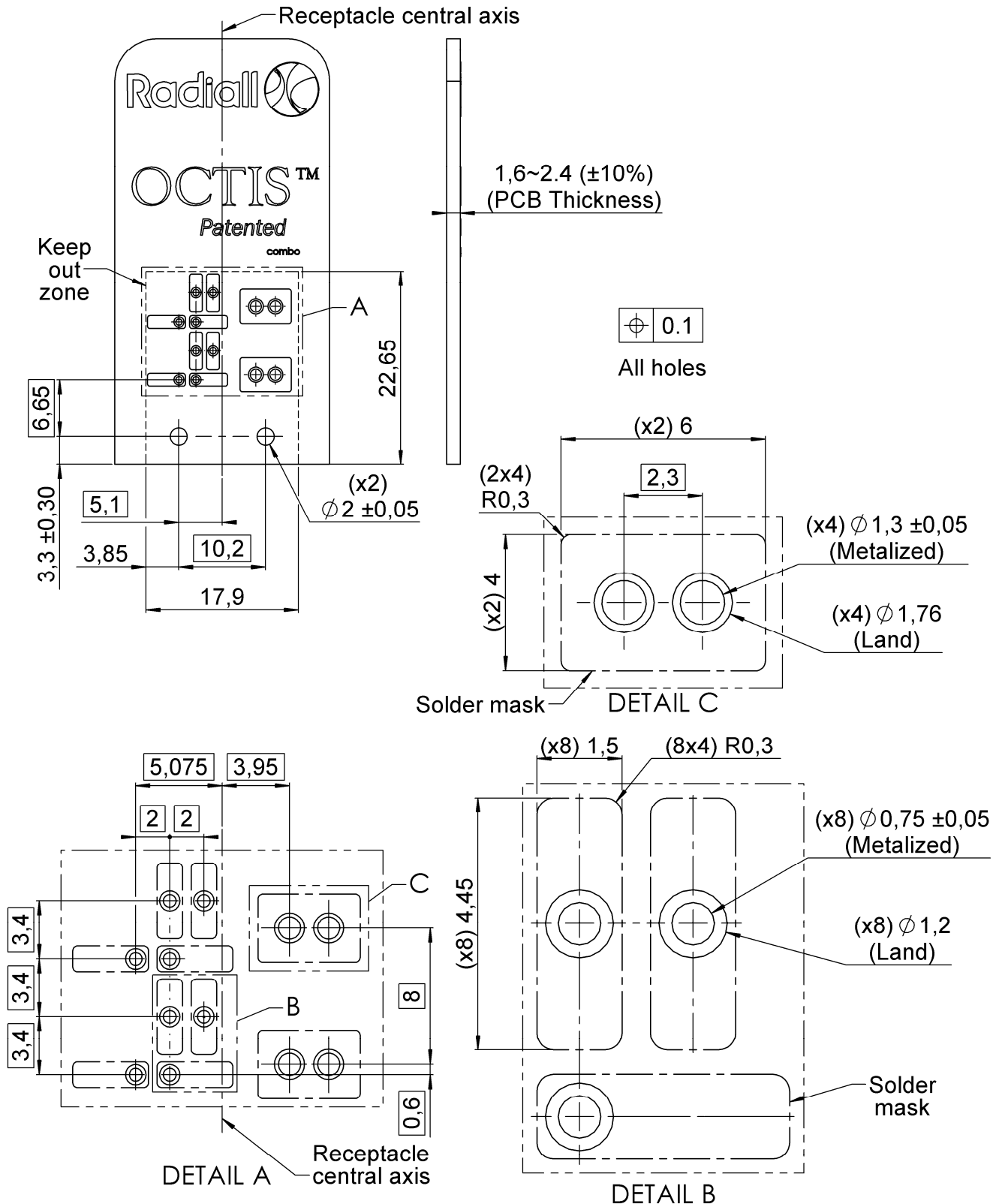
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FOOT/PRINT (General tolerance for PCB  $\pm 0.1$  mm)



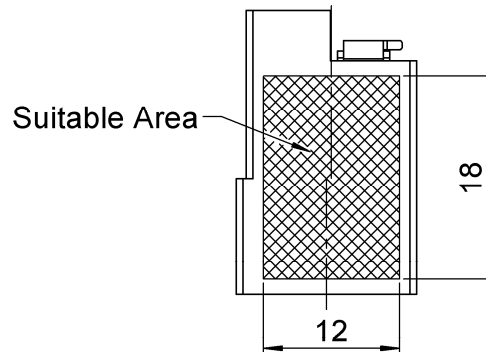
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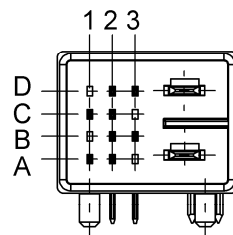
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SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



CONTACTS CONFIGURATION



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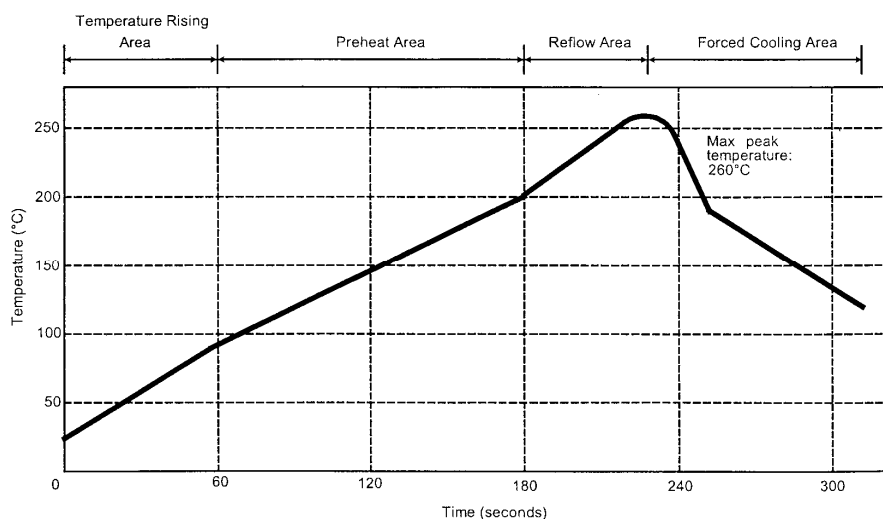
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### SOLDER PROCEDURE\*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
2. Place the component on the mounting area with a pick & place machine.  
A video camera is recommended for a good positioning of the component.  
Adhesive agents must not be used on the component.
3. This process of soldering has been tested with a convection oven.  
Below please find the typical soldering profile to use.
4. Optional cleaning of printed circuit board.
5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

### TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

\* Typical data for reflow process. Alternatively, wave soldering is also possible